

60. (New) A conductive integrated circuit metal alloy interconnection comprising an alloy of copper and silver, with silver being present in the alloy at from 50 at% to 70 at%.

61. (New) The interconnection of claim 60 wherein silver is present in the alloy at from 55 at% to 65 at%.

62. (New) The interconnection of claim 60 wherein silver is present in the alloy at about 60 at%.

63. (New) The interconnection of claim 60 having higher electromigration resistance than copper of a purity of greater than 99.999% of the same grain size.

64. (New) The interconnection of claim 60 having greater thermal stability to grain size retention and crystal orientation retention than copper of a purity of greater than 99.999% of the same grain size.